

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yuan-Tai TSENG</td> <td>09/02/2013</td> </tr> <tr> <td>Ming-Chyi LIU</td> <td>09/02/2013</td> </tr> <tr> <td>Chung-Yen CHOU</td> <td>09/02/2013</td> </tr> <tr> <td>Chia-Shiung TSAI</td> <td>09/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yuan-Tai TSENG	09/02/2013	Ming-Chyi LIU	09/02/2013	Chung-Yen CHOU	09/02/2013	Chia-Shiung TSAI	09/02/2013
Name	Execution Date										
Yuan-Tai TSENG	09/02/2013										
Ming-Chyi LIU	09/02/2013										
Chung-Yen CHOU	09/02/2013										
Chia-Shiung TSAI	09/02/2013										
RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.										
Street Address:	NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK										
City:	HSINCHU										
State/Country:	TAIWAN										
Postal Code:	300										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14019986</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14019986						
Property Type	Number										
Application Number:	14019986										
CORRESPONDENCE DATA											
Fax Number:	2027568087										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	202-756-8000										
Email:	mweipdocket@mwe.com										
Correspondent Name:	MCDERMOTT WILL & EMERY LLP										
Address Line 1:	The McDermott Building										
Address Line 2:	500 North Capitol Street, N.W.										
Address Line 4:	WASHINGTON, DISTRICT OF COLUMBIA 20001										
ATTORNEY DOCKET NUMBER:	050094-0122										
NAME OF SUBMITTER:	Stephen A. Becker										
Signature:	/stephen a. becker/										

PATENT

Date:

09/06/2013

Total Attachments: 2

source=0500940122_assignment#page1.tif

source=0500940122_assignment#page2.tif

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
INTEGRATED CIRCUIT AND MANUFACTURING AND METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

- (check one) a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- U.S. patent application Serial No. _____, filed _____
- a U.S. patent application based on PCT International Application No. _____ filed on (date) _____ (U.S. patent application Serial No. _____, if known).
- U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- (check one) U.S. patent rights only.
- Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
 (Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN 300, R.O.C.

The ASSIGNEE is:

- (check one) An individual.
- A Partnership.
- A Corporation of TAIWAN, R.O.C. (specify state or country)
- (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

